



FOR IMMEDIATE RELEASE

Aehr Test Systems

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Aehr Test Systems and Semics Inc. Announce Manufacturing and Development Partnership for FOX™ Wafer Handling and Investment by Semics in Aehr Common Stock

Fremont, CA and Seongnam, South Korea (August 24, 2016) – Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, and Semics, Inc., a semiconductor test equipment provider that produces fully automatic wafer handling and probing systems, today announced a development and manufacturing partnership between the two companies, including an investment by Semics in 200,000 shares of Aehr Test Systems common stock.

Aehr Test and Semics have a strategic partnership in place that includes a multi-year supply agreement for the development and manufacture of Aligners for Aehr Test's multi-wafer FOX test and burn-in systems. The initial products resulting from this partnership have been delivered to customers and have been successfully implemented and qualified in a production environment, and the two companies expect to collaborate on additional wafer automation projects in the future.

Gayn Erickson, President and CEO of Aehr Test Systems, commented, "We are very pleased to receive this investment in Aehr Test as part of our development and manufacturing partnership, which began several years ago when we first collaborated to develop the FOX WaferPak Aligner, a key component of our new FOX-XP Multi-Wafer Test and Burn-in Systems. We have had a very successful working relationship with Semics, and more recently worked together on the multi-stage prober for our initial FOX-1P next generation single wafer test system, which we shipped last month to our initial lead customer for this system."

Shoun Yu, CEO of Semics, commented, "This is a beneficial collaboration for both companies and we have enjoyed a very good working relationship with Aehr Test. I have enjoyed a close working relationship with Gayn that dates back many years and contributed to the success of Semics from the very beginning. We are pleased to make this investment and look forward to collaborating on additional automation projects with Aehr Test in the future."

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic and memory integrated circuits and has an installed base of more than

2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX families of test and burn-in systems and the DiePak® carrier. The ABTS system is used in production and qualification testing of packaged parts for both lower-power and higher-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company's website at www.aehr.com.

About Semics Inc.

Headquartered in Seongnam, Gyeonggi, South Korea, Semics Inc. is a leading supplier of wafer handling and probing systems for analog, mixed signal, wireless, data storage, variable sensor and memory products and has more than 15 years' experience in the worldwide market. The most important values of Semics Inc. are customer's satisfaction first and being ready for the market by inventing a product which will lead every part of the community one more step forward. With this slogan, Semics Inc. has been introducing OPUS* series wafer probe systems since 2000. Today the OPUS probe systems handle 6" to 12" bare wafer as well as thinned, singulated, and reconstructed wafers on film frames to meet market demand. The Automotive, Mobile and IoT markets are driving chip scale packaging for miniaturization, quality and reliability, and the OPUS wafer probe system is the right solution in wafer level test. For more information, please visit the Company's website at www.semics.com.

*OPUS is a trademark of Semics Inc. in Korea and other countries.

Safe Harbor Statement

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. Forward-looking statements include statements regarding Aehr Test's expectations, beliefs, intentions or strategies regarding the future including statements regarding future market opportunities and conditions, expected product shipment dates, customer orders or commitments and future operating results. The risks and uncertainties that could cause Aehr Test's results to differ materially from those expressed or implied by such forward looking statements include, without limitation, general market conditions, customer demand and acceptance of Aehr Test's products and Aehr Test's ability to execute on its business strategy. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing Aehr Test's business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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